

HSB83

Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G0187-0200Z

(Previous: ADE-208-489A)

Rev.2.00

Mar.22.2004

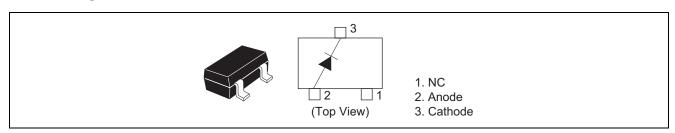
Features

- High reverse voltage. $(V_R = 250 \text{ V})$
- CMPAK package is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code	
HSB83	F7	CMPAK	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Peak reverse voltage	V_{RM}	300	V	
Reverse voltage	V _R	250	V	
Peak forward current	I _{FM}	300	mA	
Non-Repetitive peak forward surge current	I _{FSM} *1	2	А	
Average rectified current	Io	100	mA	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Note: 1. Value at duration of 10 ms.

Electrical Characteristics

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F}	_	_	1.2	V	I _F = 100 mA
Reverse current	I _{R1}	_	_	0.2	μΑ	V _R = 250 V
	I _{R2}	_	_	100		V _R = 300 V
Capacitance	С	_	_	3.0	pF	$V_R = 0 V, f = 1 MHz$
Reverse recovery time	t _{rr}	_	_	100	ns	$I_F = I_R = 30$ mA, $I_{rr} = 3$ mA, $R_L = 100$ Ω

Main Characteristics

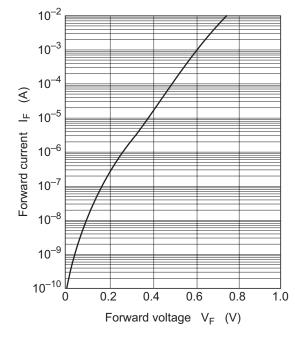


Fig.1 Forward current vs. Forward voltage

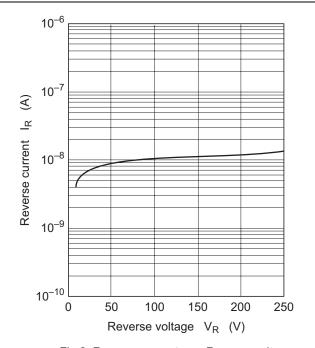
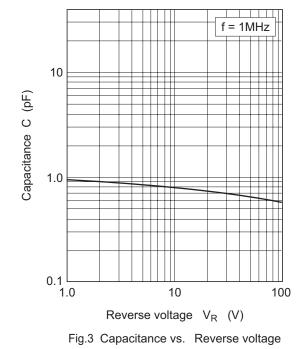
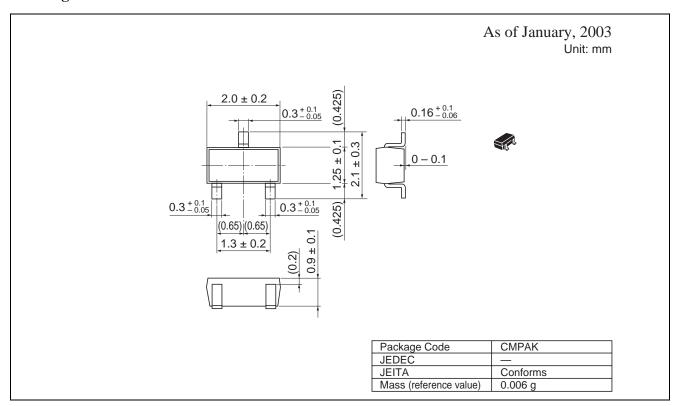


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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